

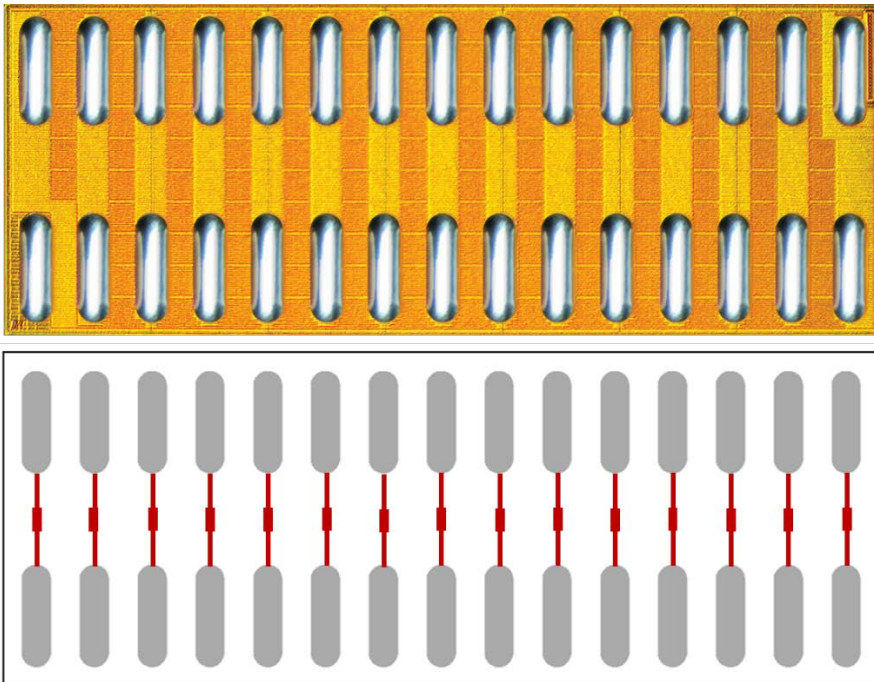
EPCDESIGNTOOL_XL-DC Mechanical Die for Daisy Chain Testing

EPCDESIGNTOOL_XL-DC are sized equivalent to EPC family of devices [EPC2020](#), [EPC2021](#), [EPC2022](#), [EPC2023](#), [EPC2024](#) with die size 6.1 mm x 2.3 mm.

Daisy chain test devices are suitable for a wide variety of process-related testing, such as life cycle testing, drop testing, thermal testing, and optimizing the assembly process.

Daisy-chained packages are wired to provide a continuous path through the package for easy testing as shown in Figure 1 below.

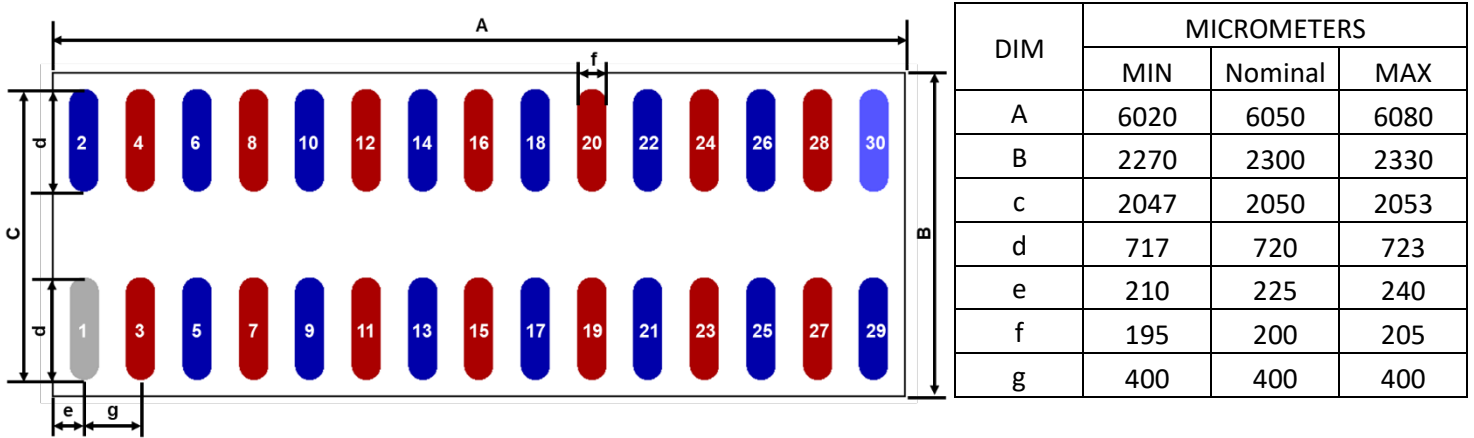
Figure 1: Daisy Chain Connections for EPCDESIGNTOOL_XL-DC



EPCDESIGNTOOL_XL-DC

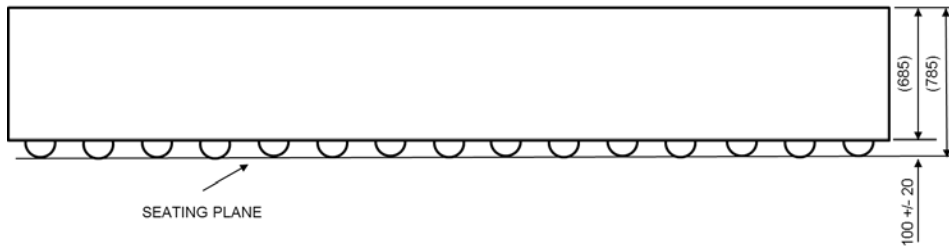
Mechanical Die for Daisy Chain Testing

Figure 2: Die Outline (Solder Bar View)



Pads 1 is Gate;
Pads 2, 5, 6, 9, 10, 13, 14, 17, 18, 21, 22, 25, 26, 29 are Source
Pads 3, 4, 7, 8, 11, 12, 15, 16, 19, 20, 23, 24, 27, 28 are Drain
Pad 30 is Substrate

Figure 3: Side View

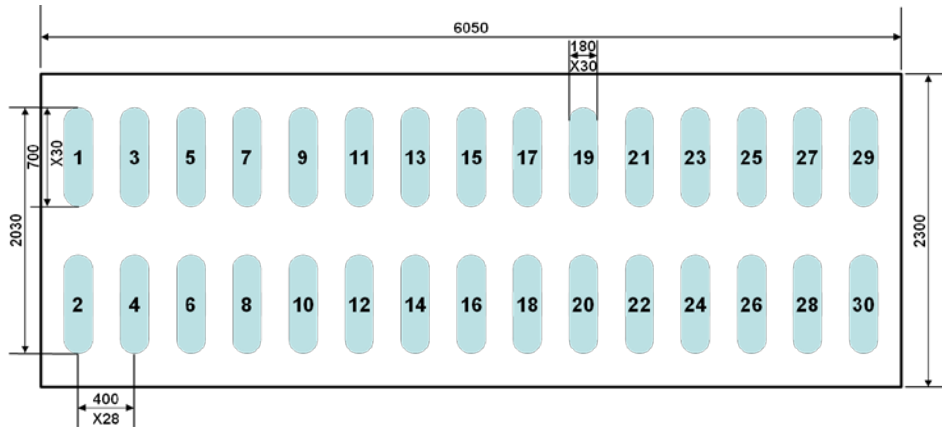


EPCDESIGNTOOL_XL-DC

Mechanical Die for Daisy Chain Testing

Figure 4: Recommended Land Pattern (units in μm)

When a daisy-chained package is assembled on the PCB, a complete circuit is formed, which allows continuity testing. The circuit includes the solder balls, the metal pattern on the die, the bond wires, and the PCB traces.



Land pattern is solder mask defined
Solder mask opening is 180 μm
It is recommended to have on-Cu trace PCB vias

Pads 1 is Gate;

Pads 2, 5, 6, 9, 10, 13, 14, 17, 18, 21, 22, 25, 26, 29 are Source

Pads 3, 4, 7, 8, 11, 12, 15, 16, 19, 20, 23, 24, 27, 28 are Drain

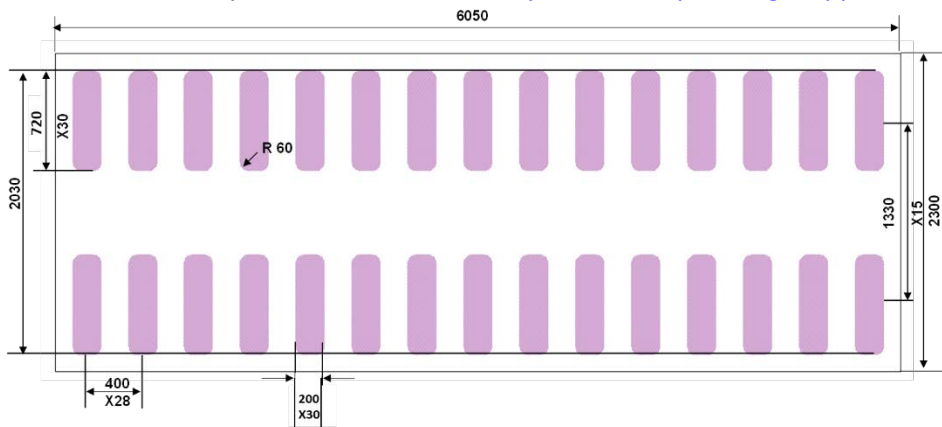
Pad 30 is Substrate

Figure 5: Recommended Stencil Pattern (units in μm)

Intended for use with SAC305 Type 3 solder.

Recommended stencil should be 4mil (100 μm) thick, must be laser cut, openings per drawing.

Additional assembly resources available at epc-co.com/epc/DesignSupport/AssemblyBasics.aspx



Efficient Power Conversion Corporation (EPC) reserves the right to make changes without further notice to any products herein. EPC does not assume any liability arising out of the application or use of any product or circuit described herein; neither does it convey any license under its patent rights, nor the rights of other.

eGaN® is a registered trademark of Efficient Power Conversion Corporation.

EPC Patent Listing: epc-co.com/epc/AboutEPC/Patents.aspx

Revised December, 2017